

## METHOD FOR MINIMIZING SLIP LINE FAULTS ON A SEMICONDUCTOR WAFER SURFACE

### ABSTRACT

5 A method for minimizing slip line faults on a surface of a semiconductor  
wafer that has been obtained using a transfer technique. The method includes  
heating the semiconductor wafer from an ambient temperature to a first higher  
temperature and pausing the heating at the first higher temperature for a time  
sufficient to stabilize the wafer. Then the wafer is heated further from the first  
higher temperature to a target higher temperature during a predetermined time  
10 interval. The further heating during an initial portion of the time interval is  
conducted at a relatively low heating rate and the heating during a final portion of the  
time interval is conducted at a relatively higher heating rate to thus minimize slip line  
faults in the surface of the wafer.

NY: 808625.1